

# **Intel® Server Board SE7501HG2 Memory List Test Report Summary**



*Revision 56.0  
July 2006*

<b>Revision History</b>		
<b>Date</b>	<b>Rev</b>	<b>Modifications</b>
Jan/03	1.0	Released document.
Jan/03	2.0	Corrected Samsung 512MB part number.
Feb/03	3.0	Added Micron 512MB part. Added Samsung 1GB part. (In shaded area)
Feb/03	4.0	Added Viking 256MB part. Added Avant, Dataram, and Samsung 512MB parts. Added DataRam 1GB part. (In shaded areas)
Mar/03	5.0	Added ATP and Dataram 1GB parts. Added Avant 512MB parts. Added ATP 256MB parts. (In shaded area)
Mar/03	6.0	Added Samsung and Micron 512MB parts. Added Samsung 1GB parts. (In shaded area)
Mar/03	7.0	Added Dataram, ATP, and Avant 1GB parts. Added Avant 512MB parts. (In shaded area)
April/03	8.0	Added ATP and Dataram 256MB parts. Added ATP and Viking 512MB parts. Added ATP and Viking 1GB parts. (In shaded area)
May/03	9.0	Added ATP 128MB parts. Added Viking, Buffalo and ATP 256MB parts. Added Viking, ATP, Buffalo and Smart 512MB parts. Added Dataram, Ma Labs and Samsung 2GB parts. (In shaded area)
June/03	10.0	Added Viking, Buffalo and Centon 256MB parts. Added Samsung 256MB and 512MB parts. (In shaded area)
June/03	11.0	Added Infineon, Avant and Legend 512MB parts. Added Buffalo and Smart 1GB parts. Added Smart 2GB parts. Added Samsung 128MB and 256MB parts. Also updated EOL status.
July/03	12.0	Added TRS 256MB parts. Added TRS and Itaucom 512MB parts. Added Legend and Avant 1GB parts. Added Samsung 256MB, 512MB and 1GB parts. Added Micron 256MB parts. (In shaded area)
July/03	13.0	Added Itaucom 256MB and 1GB parts. Added Legend and Smart 512MB parts. Added Infineon 256MB part. Added Samsung 512MB and 1GB parts. (In shaded area)
Aug/03	14.0	Added Centon 256MB parts. Added Smart and TRS 1GB parts. (In shaded area). Also Updated EOL status.
Sept/03	15.0	Added Infineon 128MB part. Added Smart 256MB parts. Added Avant and Micron 512MB parts. Added Viking and Micron 1GB parts. (In shaded area)
Sept/03	16.0	Added Avant 512MB parts. Added TRS 2GB parts. Added Infineon 128MB, 256MB, 512MB, 1GB and 2GB parts. Added Micron 128MB and 512MB parts. Added Samsung 1GB part. Added Kingston 256MB part. (In shaded area)
Oct/03	17.0	(In shaded area)
Nov/03	18.0	Added Ventura 1GB parts. Added Samsung 256MB part. Added Infineon 256MB and 512MB parts. (In shaded area) Updated "Caution" note when using stacked DRAM modules.
Nov/03	19.0	Added Legend 256MB and 512MB parts. Added ATP 512MB and 1GB parts. Added Wintec 1GB parts. Added Dataram 2GB parts. (In shaded area)
Nov/03	20.0	Added ATP 1GB parts. (In shaded area)
Dec/03	21.0	Added Smart 1GB parts. Added Legacy 1GB and 2GB parts. Updated "Note" regarding mix-memory support. (In shaded area)
Jan/04	22.0	Added Ventura and Legacy 512MB parts. Added Smart and Legend 1GB parts. (In shaded area)
Feb/04	23.0	Added Avant 512MB parts. Added Centon 1GB parts. (In shaded area). Also updated EOL status.
Feb/04	24.0	Added Dane-Elec 256MB parts. Added Avant, Swissbit and TRS 1GB parts. Added 2GB Samsung part. New CMTL address. (In shaded area)
Mar/04	25.0	Added Simple 512MB parts. Added Smart 1GB parts. (In shaded area)
Mar/04	26.0	Added Swissbit 512MB parts. Added TRS 1GB parts. Added Dataram 1GB and 2GB parts. (In shaded area) Also Updated EOL Status.
Apr/04	27.0	Added ATP, Dataram, Avant, and Legacy 1GB parts. (In shaded area)
May/04	28.0	Added ATP, Ventura, Viking, Legacy 512MB parts. Added Avant and Ventura 1GB parts. Added Smart and Ventura 2GB parts. (In shaded area)
Jun/04	29.0	Added Viking 256MB and 1GB parts. Added Ventura 1GB parts. (In shaded area)
Jun/04	30.0	Added Simple Tech 512MB parts. Added Legacy 2GB parts.
July/04	31.0	Added Kingmax 512Mb and 1GB parts. Added Smart and Viking 1GB parts. (In shaded area)
Aug/04	32.0	Added Centon 512MB parts. Added Dataram 1GB parts. (In shaded area)
Sept/04	33.0	Adding support for DDR333 modules. Added TRS, Centon and Dane-elec 512MB parts. Added Kingston, Smart and Wintec 1GB parts. Added Kingston and Dataram 2GB parts. (In shaded area)

<b>Revision History</b>		
<b>Date</b>	<b>Rev</b>	<b>Modifications</b>
Sep/04	34.0	Added Viking 1GB parts. (In shaded area)
Oct/04	35.0	Added Legend 512MB and 2GB parts. (In shaded area)
Oct/04	36.0	Added Legend 256MB. Added Smart 1GB parts. (In shaded area)
Oct/04	37.0	Added TRS and Buffalo 1GB parts. (In shaded area)
Nov/04	38.0	Added Dane, Smart and Buffalo 512MB parts. Added Dane and TRS 1GB parts. (In shaded area)
Nov/04	39.0	Added Simple, Avant, and Buffalo 512MB parts. (In shaded area)
Dec/04	40.0	Added Infineon 256MB part. Added Avant and Infineon 1GB parts. (In shaded area)
Dec/04	41.0	Added Avant 1GB and Avant 2GB parts. (In shaded area)
Dec/04	42.0	Added Buffalo and Swissbit 1GB parts. (In shaded area)
Feb/05	43.0	Added Dataram 512MB and 2GB parts. (In shaded area)
Feb/05	44.0	Added Swissbit 1GB parts. (In shaded area)
Mar/05	45.0	Added note on Lead free modules (these modules are now in bold text). Added Kingston and Swissbit 1GB parts. (In shaded area)
Apr/05	46.0	Added Avant 512MB and 1GB parts. (In shaded area)
May/05	47.0	Updated Contact information. Updated Kingston part number from KVR266X72RC25/512 to KVR266S4R25/512i per vendor's request. (In shaded area)
Aug/05	48.0	Added Kingston 512MB and 1GB parts. Added TRS 2GB parts. (In shaded area)
Aug/05	49.0	Added Kingston 2GB parts. (In shaded area)
Nov/05	50.0	Added Kingston 2GB part. (In shaded area)
Dec/05	51.0	Added SimpleTech 512MB part. (In shaded area)
Jan/06	52.0	Added Legend 2GB and 1GB parts. (In shaded area)
Jan/06	53.0	Added SimpleTech 512MB part. (In shaded area)
Feb/06	54.0	Added Dataram 1GB part. Added SimpleTech 512MB part. (In shaded area)
Mar/06	55.0	Added Kingston 1GB part. (In shaded area)
July/06	56.0	Added Smart 1GB part. (In shaded area)

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The Intel® Server Board SE7501HG2 may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

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**Please Note:** DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar memory manufacturer and similar speeds in each bank on the memory module is NOT recommended.

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## Overview of Memory Testing

The following procedure is used to test memory modules for use in the Intel® Server Board SE7501HG2. Memory is a vital subsystem in a platform. Intel Corporation requires strict guidelines to be met before a memory vendor and part is put onto the qualified memory list. Each Intel Server Board product has a separate qualified memory list.

Memory qualification for Intel's Server Board products is performed by Intel's Memory Validation Laboratory (MVL), and by an independent external test laboratory, Computer Memory Test Lab (CMTL)<sup>1</sup>. CMTL is a leading memory testing organization responsible for testing a broad range of memory products. Memory devices tested by Intel's MVL or CMTL must undergo rigorous tests to ensure that the product will perform the intended server functions.

Intel®'s Server and Workstation Board qualified memory lists categorize memory modules as Advanced Tested. The Advanced Testing process involves a paper qualification, a standard voltage and room temperature functional test, and a voltage and temperature margin functional test. A paper qualification is a review of critical timings, electrical characteristics, timing requirements, environmental requirements, and packaging requirements in order to see if the memory meets Intel's memory specifications. The standard voltage and room temperature test involves testing the memory module on the particular Intel board for which it is being qualified with test software operating under Microsoft\* Windows\* 2000 Advanced Server for no less than 24 hours. The voltage and temperature margin testing involves testing the memory module on the particular Intel board for which it is being qualified with various test software and operating systems for 48-72 hours under various voltage and temperature margin conditions. Memory modules that have completed Advanced Testing are known to be compatible with the product on which they were tested, and with the test software and operating system that was utilized during the test procedure.

For information regarding the testing procedure required to reach each phase, please contact your Intel Representative.

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<sup>1</sup> CMTL is an independent memory testing organization responsible for testing a broad range of memory products. Receiving a "PASS" after being tested by CMTL, means that a product functions correctly and consumers can use it to perform the intended server functions. In order to pass these stringent standards, memory products must maintain the highest manufacturing procedures and pass an exacting battery of tests. Testing is performed with equipment and a procedure as defined by Intel's various functional testing levels. CMTL contact:

Office: (949) 716-8690

Fax (949) 716-8691

Computer Memory Test Lab (CMTL)

24 Hammond Suite F

Irvine, CA 92618

<http://www.cmtlabs.com/>

## Qualified Memory for the Intel® Server Board SE7501HG2

The memory module on the server board SE7501HG2 has 6 DIMM sockets, which can hold up to 12 GB of Registered DDR266 or DDR333 memory using six 72-bit DIMM modules. The following memory features are supported:

- DDR266 and DDR333 registered ECC compatible 2.5V modules (in compliance with the DDR JEDEC DIMM Specification).
- DIMMs with capacity of 128MB, 256MB, 512MB, 1GB and 2GB. Other DRAM sizes may function correctly but will not be validated.
- Minimum configuration is 256MB using two 128MB DIMMs.

The memory controller in the E7501 chip set supports memory scrubbing, single-bit error correction and multiple-bit error detection and the Intel® Single Device Data Correction feature. Memory can be implemented with either single sided (one row) or double-sided (two row) DIMMs. The Intel® Single Device Data Correction architecture gives the memory sub-system the ability to withstand a multi-bit failure within a DRAM device, including a failure that causes incorrect data on all data bits of the device.

**Note:** Intel does not test, recommend, or support mixing of memory types within the same server system. Functionality issues may occur if mixed memory types are installed in the same server system. Intel recommends that memory modules of identical size, type, banking and stacking technology, and vendor are installed in each server system. Intel will not provide support for issues encountered when mixed memory configurations are in use.

Due to the Intel® SE7501HG2 DDR 266 DIMM Slew Rate Observation Sighting issue that is documented in TA 639-x, Intel recommends that customers utilize SE7501HG2 BIOS P05 or later versions on the SE7501HG2 server board. Please reference TA 639-x for further information on this issue.

Intel does not test, recommend, or support any mixing of memory types within the same server systems. However, if the customer chooses to utilize mixed memory configurations, the following guidelines should be observed: Certain mixed memory configurations violate the Intel® E7501 chipset specification for DDR write ring back when installed in the SE7501HG2 server board. Mixed memory configurations with both Double-Banked (DB) and Single-Banked (SB) DIMMs installed require that the SB DIMMs must be installed in the lowest numbered memory slots (memory slots furthest from the MCH). Mixed memory configurations with SB DIMMs installed in the highest numbered memory slots (memory slots closest to the MCH) and DB DIMMs installed in the lowest numbered memory slots are detected by the SE7501HG2 BIOS, and a POST error message will be displayed instructing the user to reorder their DIMM pairs. The following mixed memory configurations will cause the BIOS to display a POST error message when installed:

DIMM 1A & 1B	DIMM 2A & 2B	DIMM 3A & 3B	
DB	SB	Empty	Invalid: violates write ring back spec
DB	DB	SB	Invalid: violates write ring back spec
DB	SB	SB	Invalid: violates write ring back spec
DB	SB	DB	Invalid: violates write ring back spec
SB	DB	SB	Invalid: violates write ring back spec
Empty	Empty/SB/DB	Empty/SB/DB	Invalid: DIMMs must be populated starting with pair 1A/1B, then 2A/2B, then 3A/3B
SB/DB	Empty	SB/DB	Invalid: DIMMs must be populated starting with pair 1A/1B, then 2A/2B, then 3A/3B

**How to identify if you have Single-Banked or Double-Banked modules:**

**x8SB** = x8 Single-Banked modules have 5 DRAMs on the front and 4 DRAMs on the back with empty spots in between the DRAMs.

**x8DB** = x8 Double-Banked modules have 9 DRAMs on each side for a total of 18 (no empty slots)

**x4SB** = x4 Single-Banked modules have 9 DRAMs on each side for a total of 18, and look similar to x8 Double-Banked

**x4DB** = x4 Double-Banked modules have 18 (stacked) DRAMs on each side for a total of 36

Below is a chart that lists the current supported memory types:

<b>DDR266 Registered DRAM Module Configurations Matrix</b>					
<b>DIMM Capacity</b>	<b>DIMM Organization</b>	<b>DRAM Density</b>	<b>DRAM Organization</b>	<b># DRAM Devices/rows/Banks</b>	<b># Address bits rows/Banks/column</b>
128MB	16M x 72	64Mbit	16M x 4	18/1/4	12/2/10
128MB	16M x 72	64Mbit	8M x 8	18/2/4	12/2/9
128MB	16M x 72	128Mbit	16M x 8	9/1/4	12/2/10
256MB	32M x 72	64Mbit	16M x 4	36/2/4	12/2/10
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	128Mbit	32M x 4	36/2/4	12/2/11
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
1GB	128M x 72	256Mbit	64M x 4	36/2/4	13/2/11
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12
2GB	256M x 72	512Mbit	128M x 4	36/2/4	13/2/12
<b>DDR333 Registered DRAM Module Configuration Matrix</b>					
256MB	32M x 72	128Mbit	32M x 4	18/1/4	12/2/11
256MB	32M x 72	128Mbit	16M x 8	18/2/4	12/2/10
256MB	32M x 72	256Mbit	32M x 8	9/1/4	13/2/10
512MB	64M x 72	256Mbit	64M x 4	18/1/4	13/2/11
512MB	64M x 72	256Mbit	32M x 8	18/2/4	13/2/10
512MB	64M x 72	512Mbit	64M x 8	9/1/4	13/2/11
1GB	128M x 72	512Mbit	128M x 4	18/1/4	13/2/12
1GB	128M x 72	512Mbit	64M x 8	18/2/4	13/2/11
1GB	128M x 72	1Gbit	128M x 4	9/1/4	14/2/11
2GB	256M x 72	1Gbit	128M x 4	18/1/4	14/2/12
2GB	256M x 72	1Gbit	128M x 8	18/2/4	14/2/11



Memory features are detailed in the *Intel® Server Board SE7501HG2 Technical Product Specification* available on-line at <http://support.intel.com/support/motherboards/server/SE7501HG2>

The following table lists DIMM devices known to be compatible with the Intel Server Board SE7501HG2. Intel recommends that Advanced Tested DIMMs be used to establish reliable system operation. DIMM devices not listed can be used; but, in the event of unreliable system operation, the DIMM devices should be replaced with functionally Advanced Tested DIMMs to determine whether the DIMM devices are causing the problem.

**Caution:** Third party memory vendors may use the same module part number with different DRAM vendors and die revisions. To insure proper system operation, verify that each DRAM vendor and die revision has been separately tested and qualified. Please notify CMTL if there is a discrepancy.

**Note:** This list is not intended be all-inclusive. It is provided as a convenience to Intel's general customer base, but Intel does not make any representations or warranties whatsoever regarding the quality, reliability, functionality, or compatibility of these memory modules.

***This list is subject to change without notice.***

**Server Board SE7501HG2**  
**Registered, ECC, DDR266 DIMM Modules**  
**128MB Sizes (16Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
Micron	MT9VDDT1672G-265B2	MT46V16M8-75B	Micron		12/17/02	2.5	Yes	(16Mx8)*9	x8SB	
Samsung	M312L1713D T0-CA2	K4H280838D -TCA2	Samsung		11/22/02	2	Yes	(16Mx8)*9	x8SB	
+ATP Electronics	AB16L72A8S EB0S	K4H280838D -TCB0 rev D	Samsung	SB184A0 8L rev 1	4/9/03	2.5		(16Mx8)*9	x8SB	EOL
Samsung	M312L1713E TS-CA2	K4H280838E -TCA	Samsung		6/2/03	2	Yes	(16Mx8)*9	x8SB	
Samsung	M383L1713E TS-CB0	K4H280838E -TCB0	Samsung		6/9/03	2.5		(16Mx8)*9	x8SB	
Infineon	HYS72D1650 0GR-7-A	HYB25D1288 00AT-7	Infineon		8/25/03	2	Yes	(16Mx8)*9	x8SB	
Infineon	HYS72D1600 0GR-7-A	HYB25D1288 00AT-7A	Infineon		9/8/03	2		(16Mx8)*9	x8SB	
Micron	MT9VDDT1672G-265B1	MT46V16M8-75 B	Micron		9/19/03	2.5		(16Mx8)*9	x8SB	

*Modules shaded in blue are low profile.*

*Modules in bold text do not contain Lead.*

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Server Board SE7501HG2**  
**Registered, ECC, DDR266 DIMM Modules**  
**256MB Sizes (32Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EO L
Micron	MT9VDDT3272G-265B2	MT46V32M8-75B	Micron		12/23/02	2.5	Yes	(32Mx8)*9	x8SB	
Samsung	M312L3310DT0-CA2	K4H280438D-TCA2	Samsung		12/23/02	2	Yes	(32Mx4)*18	x4SB	
+Viking	VI4CR327224CTH L1	K4H280438D-TCB0 rev D	Samsung	03-0291 Rev A	2/19/03	2.5	Yes	(32Mx4)*18	x4SB	EOL
+ATP Electronics	AB32L72R4S4B0S	K4H280438C-TCB0 rev C	Samsung	SB184R04L1	3/10/03	2.5	Yes	(32Mx4)*18	x4SB	EOL
+ATP Electronics	AB32L72Q8SQB0 S	K4H560838D-TCB0 rev D	Samsung	SB184Q08L1	4/4/03	2.5	Yes	(32Mx8)*9	x8SB	EOL
+Dataram	DTM63640B	MT46V32M4TG-75 rev B	Micron	40581A rev A	4/4/03	2.5	Yes	(32Mx4)*18	x4SB	
+Viking	VI4CR327228DTH L2	MT46V32M8TG-75 rev B	Micron	0000905A	4/17/03	2.5	Yes	(32Mx8)*9	x8SB	EOL
Infineon	^HYS72D32300G BR-7F-B	K4H560838D-TCAA	Infineon		4/22/03	2	Yes	(32Mx8)*9	x8SB	
Samsung	^M312L3223DT0-CAA	K4H560838D-TCAA	Samsung		4/22/03	2	Yes	(32Mx8)*9	x8SB	
+Buffalo	DD266-R256/SD	K4H280838D-TCB0 rev D	Samsung	RCE0501-AB	4/22/03	2.5		(16Mx8)*18	x8DB	
+ATP Electronics	AB32L72A8S4B0S	K4H280838D-TCB0 rev D	Samsung	SB184A08L rev1	4/9/03	2.5		(16Mx8)*18	x8DB	EOL
+Buffalo	DD266L-RS256/SD	K4H560838D-TCB0 rev D	Samsung	1D188EF-AA	4/25/03	2.5	Yes	(32Mx8)*9	x8SB	
+Viking	VI4CR327228DTH L3	MT46V32M8TG-75 rev C	Micron	0000905A	5/12/03	2.5	Yes	(32Mx8)*9	x8SB	
+Buffalo	DD266L-RS256/SD	K4H560838D-TCB0 rev D	Samsung	1D188EF-AA	4/25/03	2.5	Yes	(32Mx8)*9	x8SB	
+Buffalo	DD266-R256/SE	K4H280838E-TCB0 rev E	Samsung	RCE0502-AA	4/30/03	2.5		(16Mx8)*18	x8DB	
+Centon Electronics	TOP02-D007G	MT46V32M4TG-75 rev B	Micron	LE36DDT184 4R rev A	5/19/03	2.5	Yes	(32Mx4)*18	x4SB	EOL
Samsung	M383L3310ETS-CB0	K4H280438E-TCB0	Samsung		5/19/03	2.5		(16Mx8)*18	x8DB	
Samsung	^M312L3223ETS-CAA	K4H560838E-TCAA	Samsung		6/17/03	2	Yes	(32Mx8)*9	x8DB	
+TRS* Tele-Radio-Space GmbH	TRS21150	HYB25D256800 BT-7 rev B	Infineon	M0529LA1 rev 1	6/18/03	2	Yes	(32Mx8)*9	x8DB	
Samsung	M312L3223ETS-CA2	K4H560838E-TCCA2	Samsung		6/20/03	2	Yes	(32Mx8)*9	x8SB	
Micron	MT9VDDT3272G-265C3	MT46V32M8-75 C	Micron		6/25/03	2.5	Yes	(32Mx8)*9	x8SB	
ITAUCOM	256E2665R28	ICM4L560807-65	Micron	0247 A	6/30/03	2.5	Yes	(32Mx8)*9	x8SB	
Infineon	HYS72D32501GR-7-A	HYB25D128400 AT-7	Infineon		7/10/03	2		(32Mx4)*18	X4SR	

**Registered, ECC, DDR266 DIMM Modules  
256MB Sizes (32Mx72)**

<b>Manufacturer</b>	<b>Part Number</b>	<b>DRAM Part Number</b>	<b>DRAM Vendor</b>	<b>PCB Part Number</b>	<b>Date</b>	<b>CAS Latency</b>	<b>Low Profile</b>	<b>DRAM Organization</b>	<b>Bank</b>	<b>EOL</b>
+Centon Electronics	TOP02-D004D	MT46V32M4TG-75 rev B	Micron	LE36DDT184 4R rev A	7/24/03	2.5	Yes	(32Mx4)*18	x4SB	EOL
+Smart Modular Technologies	SM3272RDDR320 LP-I	HYB25D256800 BT-7 rev B	Infineon	184-L13-2	8/20/03	2	Yes	(32Mx4)*18	x4SB	
Kingston	KVR266X72RC25/256	MT46V32M8-75C	Micron		9/8/03	2.5	Yes	(32Mx8)*9	x8SB	
Infineon	HYS72D32000GR-7-B	HYB25D256800 BT-7	Infineon		9/8/03	2		(32Mx8)*9	x8SB	
+Legend	L3272YC5-RU1HDC5B	HY5DU56822BT -J rev B	Hyundai	DRR1U0818-A rev 1	10/27/03	2.5	Yes	(32Mx8)*9	x8SB	
+Dane-Elec	ODLD266R072325 I-1MC	MT46V32M8TG-6T rev C	Micron	DR1G872-A rev A	1/30/04	2.5	Yes	(32Mx8)*9	x8SB	
+Viking	VI4CR327228DTH L4	MT46V32M8TG(P)-6T rev G	Micron	0000985A	5/12/04	2.5	Yes	(32Mx8)*9	x8SB	

**Registered, ECC, DDR333 DIMM Modules  
256MB Sizes (32Mx72)**

<b>Manufacturer</b>	<b>Part Number</b>	<b>DRAM Part Number</b>	<b>DRAM Vendor</b>	<b>PCB Part Number</b>	<b>Date</b>	<b>CAS Latency</b>	<b>Low Profile</b>	<b>DRAM Organization</b>	<b>Bank</b>	<b>EOL</b>
+Legend	L3272YC6-RU1HDC5B	HY5DU56822BT -D43 rev B	Hyundai	DRR1U0818-A rev 1	10/5/04	2.5	Yes	(32Mx8)*9	x8SB	
Infineon	HYS72D32300GB R-6-C		Infineon		11/5/04	2.5	Yes	(32Mx8)*9	X8SB	

*Modules shaded in blue are low profile.*

**Modules in bold text do not contain Lead.**

(^) This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Server Board SE7501HG2**  
**Registered, ECC, DDR266 DIMM Modules**  
**512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
Infineon	HYS72D64500GR-7-A	HYB25D256400AT-7	Infineon		12/17/02	2	Yes	(64Mx4)*18	x4SB	
Infineon	^HYS72D64500GR-7F-B	HYB25D256400BT-7F	Infineon		12/23/02	2	Yes	(64Mx4)*18	x4SB	
Infineon	HYS72D64000GR-7-B	HYB25D256400BT-7	Infineon		1/20/03	2		(64Mx4)*18	x4SB	
Samsung	^M312L6420DT0-CAA	K4H560438D-TCAA	Samsung		1/6/03	2	Yes	(64Mx4)*18	x4SB	
Samsung	M312L6420DT0-CA2	K4H560438D-TCA2	Samsung		1/8/03	2	Yes	(64Mx4)*18	x4SB	
+Avant Technology	AVM7264R38C22-66K0-A	NT5DS64M4AT-7K rev A	Nanya	50-1415-01 rev B	2/19/03	2	Yes	(64Mx4)*18	x4SB	EOL
+Dataram	DTM63641E	HYB25D256400BT-7 rev B	Infineon	40581A rev A	2/17/03	2.5	Yes	(64Mx4)*18	x4SB	EOL
+Avant Technology	AVM7264R39C22-66K1-A	NT5DS32M8AT-7K rev A	Nanya	501411-01A rev A	2/25/03	2	Yes	(32Mx8) *18	x8DB	EOL
+Dataram	DTM63641G	MT46V64M4TG-75 rev C	Micron	40581A rev A	2/28/03	2.5	Yes	(64Mx4)*18	x4SB	
+ATP Electronics	AB64L72R4S8B0S	K4H560438D-TCB0 rev D	Samsung	SB184R04L1	3/4/03	2.5	Yes	(64Mx4)*18	x4SB	EOL
+Viking	VI4CR647224DT-HL1	K4H560438D-TCB0 rev D	Samsung	03-0291 rev A	3/3/03	2.5	Yes	(64Mx4)*18	x4SB	EOL
+Avant Technology	AVM7264R38C52-66K0-A	MT46V64M4TG-75 B rev B	Micron	50-1415-01 rev B	3/6/03	2.5	Yes	(64Mx4)*18	x4SB	EOL
Samsung	M383L6420DTS-CA2	K4H560438D-TCA2	Samsung		1/20/03	2		(64Mx4)*18	x4SB	
Micron	MT18VDDT6472G-265B1	MT46V64M4-75 B	Micron		1/29/03	2.5		(64Mx4)*18	x4SB	
+ATP Electronics	AB64L72Q8S8B0S	K4H560838D-TCB0 rev D	Samsung	SB184Q08L1 rev 1	3/28/03	2.5	Yes	(32Mx8) *18	x8DB	EOL
+Viking	VI4CR647228DT-HL1	K4H560838D-TCB0 rev D	Samsung	0000905AG	3/26/03	2.5	Yes	(32Mx8) *18	x8DB	EOL
+Viking	VI4CR647228DT-HL2	K4H560838D-TCB0	Samsung	0000905A	4/14/03	2.5	Yes	(32Mx8) *18	x8DB	EOL
+ATP Electronics	AB64L72A8S8B0S	K4H560838D-TCB0 rev D	Samsung	SB184A08L rev1	4/17/03	2.5		(32Mx8) *18	x8DB	EOL
+Buffalo	DD266-R512/SD	K4H560838D-TCB0 rev D	Samsung	RCE0501-AB	4/22/03	2.5		(32Mx8) *18	x8DB	
+Buffalo	DD266-R512/MB	MT46V32M8-75 rev B	Micron	RCE0501-AB	4/22/03	2.5		(32Mx8) *18	x8DB	
Samsung	M383L6420DTS-CB0	K4H560438D-TCB0	Samsung		4/22/03	2.5		(64Mx4)*18	x8DB	
+Smart Modular Technologies	SM6472RDDR3H1LP-N	NT5DS64M4AT-7K	Nanya	P52G184NE SZ6G001 rev A	4/9/03	2.5	Yes	(64Mx4)*18	x8DB	
+ATP Electronics	AB64L72A8S8B0	NT5DS32M8AT rev D	Nanya	SB184A08L rev1	5/2/03	2.5		(32Mx8) *18	x8DB	EOL

**Registered, ECC, DDR266 DIMM Modules  
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Viking	VI4CR647224DT HL2	MT46V64M4TG-75 rev B	Micron	03-0291 rev A	5/7/03	2.5	Yes	(64Mx4)*18	x4SB	EOL
+Buffalo	DD266L-R512/SD	K4H560838D-TCB0 rev D	Samsung	1D188EF-AA	5/12/03	2.5	Yes	(32Mx8)*18	x8DB	
+Viking	VI4CR647228DT HL4	MT46V32M8TG-75 rev C	Micron	0000905A rev A	5/14/03	2.5	Yes	(32Mx8)*18	x8DB	
+Avant Technology	AVM7264R38C52 66K0-A	MT46V64M4TG-75 C rev C	Micron	50-1415-01-B rev B	6/5/03	2.5	Yes	(64Mx4)*18	x4SB	EOL
Samsung	M312L6420ETS-CA2	K4H560438E-TCA2	Samsung		5/23/03	2	Yes	(64Mx4)*18	x4SB	
Infineon	HYS72D64320GB R-7-B	HYB25D256800 BC-7	Infineon		6/9/03	2	Yes	(32Mx8) *18	x8DB	
+Legend	L6472TC5-RR2HDC5A	HY5DU56822AT -H rev A	Hyundai	DRR720818A rev 2	6/10/03	2.5		(32Mx8) *18	x8DB	EOL
+TRS* Tele-Radio-Space GmbH	TRS21151	HYB25D256400 BT-7 rev B	Infineon	M0530LA1 rev 1	6/23/03	2	Yes	(64Mx4) *18	x4SB	
+TRS* Tele-Radio-Space GmbH	TRS21152	HYB25D256800 BT-7 rev B	Infineon	M0529LA1 rev 1	6/23/03	2	Yes	(32Mx8) *18	x8DB	
ITAUCOM	512E2665R24	ICM4L560407-65	Micron	0269 A	6/25/03	2.5	Yes	(64Mx4) *18	x4SB	
Samsung	M312L6420ETS-CAA	K4H560438E-TCAA	Samsung		6/23/03	2	Yes	(64Mx4)*18	x4SB	
+Legend	L6472YC5-PPASDC5D	K4H560438D-TCB0 rev D	Samsung	18-25141A rev A	7/9/03	2.5	Yes	(64Mx4)*18	x4SB	EOL
+Smart Modular Technologies	SM6472RDDR32 0LP-I	HYB25D256400 BT-7 rev B	Infineon	184-M12-2	7/3/03	2	Yes	(64Mx4)*18	x4SB	
Samsung	M383L6420ETS-CB0	K4H560438E-TCB0	Samsung		7/28/03	2.5		(64Mx4)*18	x4SB	
Micron	MT18VDDT6472 G-265C3	MT46V64M4-75 C	Micron		8/25/03	2.5	Yes	(64Mx4)*18	x4SB	
Kingston	KVR266S4R25/512i	HYB25D256400 BT-7	Infineon		9/2/03	2.5	Yes	(64Mx4)*18	x4SB	
+Avant Technology	AVM7264R38C52 66K0-A	NT5DS64M4BT-75B rev B	Nanya	50-1415-01-B rev B	8/26/03	2.5	Yes	(64Mx4)*18	x4SB	
Infineon	HYS72D64500GR -7-B	HYB25D256400 BT-7	Infineon		9/8/03	2	Yes	(64Mx4)*18	x4SB	
Micron	MT18VDDT6472 G-262C3	MT46V64M4-75E C	Micron		9/16/03	2	Yes	(64Mx4)*18	x4SB	
Infineon	MHYS72D64300G BR-7F-B	HYB25D256400 BC-7F	Infineon		9/19/03	2	Yes	(64Mx4)*18	x4SB	
Micron	MT18VDDF6472 G-265C1	3NCII D9BHV	Micron		9/23/03	2.5	Yes	(64Mx4)*18	x4SB	
+Legend	L6472YC5-RU1HDC5B	HY5DU56822BT -J rev B	Hyundai	DRR1U0818-A rev 1	10/27/03	2.5	Yes	(32Mx8)*18	x8DB	

**Registered, ECC, DDR266 DIMM Modules  
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Legend	L6472YC5-182HDD5A	HY5DU56422AT-K rev A	Hyundai	184RL rev 2	10/16/03	2.5	Yes	(64Mx4)*18	x4SB	
ATP Electronics	AB64L72Q8S8B0S	K4H560838E-TCB3 rev E	Samsung	SB184Q08L1	10/21/03	2.5	Yes	(32Mx8) *18	x8DB	
+Ventura Technology Group	D52WVK25SV	K4H560838E-TCB3 rev E	Samsung	V208	12/24/03	2.5	Yes	(32Mx8) *18	x8DB	
+Legacy Electronics Inc.	88L6JDLR-1LDG	LED64408TA-6	Legacy	LE36DDT1844R rev A	12/12/03	2.5	Yes	(64Mx4)*18	x4SB	
+Avant Technology	AVM7264R39C5266K1-A	MT46V32M8TG-75 rev G	Micron	50-1411-01-A rev A	1/21/04	2.5	Yes	(32Mx8) *18	x8DB	
SimpleTech	ST72E8F64-A75ES	K4H560838E-TCCC rev E	Samsung	1047	2/24/04	2.5	Yes	(32Mx8) *18	x8DB	
+Swissbit	SDR06472D1B221N-75	HYB25D256800BT-6 rev B	Infineon	BRDA80A	3/5/04	2	Yes	(32Mx8) *18	x8DB	
+ATP Electronics	AB64L72Q8S8B0S	K4H560838F-TCB3 rev F	Samsung	SB184Q08L1 rev 1	4/29/04	2.5	Yes	(32Mx8) *18	x8DB	
+Viking	VI4CR647228DTHL5	MT46V32M8TG(P)-6T rev G	Micron	0000985A	4/29/04	2.5	Yes	(32Mx8) *18	x8DB	
+Ventura Technology Group	D52WVK25MV3	MT46V32M8TG-6T rev C	Micron	V208	4/21/04	2.5		(32Mx8) *18	x8DB	
+Legacy Electronics Inc.	88S6JDLR-1JDG	HYB25D256400BT-7 rev B	Infineon	LE36DDT1844R rev A	4/23/04	2	Yes	(64Mx4)*18	x4SB	
SimpleTech	ST72E4K64-A75EC	M2S56D20ATP	Elpida	E187565	6/2/04	2.5	Yes	(64Mx4)*18	x4SB	
Kingmax	MPNC22D-38ST3-SBJ	K4H560838E-TCB3 rev E	Samsung	BRDA80A	6/21/04	2.5	Yes	(32Mx8) *18	x8DB	
+Centon Electronics	TOP02-E008H	MT46V64M8TG(P)-6T rev C	Micron	DR1G872 rev A	7/22/04	2	Yes	(64Mx8)*9	x8SB	
+TRS	TRS21202	HYB25D256400CE-7 rev C	Infineon	M0530LA1 rev 1	8/11/04	2	Yes	(64Mx4)*18	x4SB	
+Dane-Elec	DLD266R072642H	HYB25D256400BT-7 rev B	Infineon	0303	7/28/04	2	Yes	(64Mx4)*18	x4SB	
+Centon Electronics	TOP02-E007G	MT46V64M8TG(P)-6T rev C	Micron	DR1G872 rev A	7/27/04	2.5	Yes	(64Mx8)*9	x8SB	
+Legend	L6472YC5-PPASDD5D	K4H560438D-TCB3 rev D	Samsung	18-25141A Rev A	9/22/04	2.5	Yes	(64Mx4)*18	x4SB	
+Dane-Elec	DLD266R072642H	MT46V64M4TG(P)-6T rev G	Micron	0303	11/4/04	2	Yes	(64Mx4)*18	x4SB	
+Smart Modular Technologies	SM6472RDDR325LP-S	K4H560438E-TCB0 rev E	Samsung	M312L3310 ETS	11/12/04	2.5	Yes	(64Mx4)*18	x4SB	
SimpleTech	ST72E4K64-A75EC	K4H560438E-TCB0 rev E	Samsung	1183 rev A	11/19/04	2.5	Yes	(64Mx4)*18	x4SB	
+Avant Technology	AVM7264R39C5266K1-MVA	V58C2256804SAT5B rev A	Mosel Vitelic	50-1411-01-A rev A	11/15/04	2.5	Yes	(32Mx8) *18	x8DB	
+Dataram	DTM63662C	HYB25D256400CE-7 rev C	Infineon	40581A rev A	1/26/05	2	Yes	(64Mx4)*18	x4SB	
SimpleTech	ST72E4K64-A75EC	K4H560438E-TCB3 rev E	Samsung	1183 rev A	11/30/05	2.5	Yes	(64Mx4)*18	x4SB	
<b>SimpleTech</b>	<b>ST72E4K64-A75EC</b>	<b>HYB25D256400CT-6 rev C</b>	<b>Infineon</b>	<b>01183 rev A</b>	<b>12/23/05</b>	<b>2.5</b>	<b>Yes</b>	<b>(64Mx4)*18</b>	<b>x4SB</b>	
SimpleTech	ST72E4K64-A75EC	MT46V64M4TG-6T rev G	Micron	01183 rev A	1/23/06	2.5	Yes	(64Mx4)*18	x4SB	

**Registered, ECC, DDR333 DIMM Modules  
512 MB Sizes (64Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Buffalo	DD333L-R512/MG	MT46V32M8T G(P)-6T rev G	Micron	1D188EF-AA	11/10/04	2.5	Yes	(32Mx8)*18	x8DB	
+Buffalo	DD333L-R512/SF	K4H560838F-TCB3 rev F	Samsung	1D188EF-AA	11/17/04	2.5	Yes	(32Mx8)*18	x8DB	
+Avant Technology	AVM7264R52C5333K1-MTD	MT46V64M8T G-6T rev D	Micron	50-1411-01-A rev A	4/8/05	2.5	Yes	(64Mx8)*9	x8SB	
+Kingston	KVR333S4R25/512I	K4H560438E-GCB3 rev E	Samsung	2025161-001.B00 na	7/14/05	2.5	Yes	(64Mx4)*18	x4SB	
+Kingston	KVR333S4R25/512I	HYB25D25640 OCC-6 rev C	Infineon	2025161-001.B00	7/6/05	2.5	Yes	(64Mx4)*18	x4SB	

*Modules shaded in blue are low profile.*

**Modules in bold text do not contain Lead.**

(^) This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>



**Server Board SE7501HG2**  
**Registered, ECC, DDR266 DIMM Modules**  
**1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
Infineon	HYS72D128500GR-7-A	HYB25D512400AT-7	Infineon		1/6/03	2	Yes	(128Mx4)*18	x4SB	
+Dataram	DTM63653B	HYB25D256400BC-7 rev B	Infineon	40599A rev A	2/26/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+Dataram	DTM63621F	HYB25D256400BT-7 rev B	Infineon	40556 rev B	3/10/03	2	Yes	(64Mx4)*36	x4DB	
+ATP Electronics	AB28L72P4SMB0A	NT5DS64M4AT-7K	Nanya	SB184P04 L1 rev 1	3/6/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
Samsung	M312L2828DT0-CA2	K4H560438D-TCA2	Samsung		11/25/02	2	Yes	(64Mx4)*36	x4DB	
Samsung	M312L2828DT0-CAA	K4H510638D-TCAA	Samsung		2/18/02	2	Yes	(64Mx4)*36	x4DB	
Samsung	M383L2828DT1-CA2	K4H560438D-TCA2	Samsung		3/5/02	2		(64Mx4)*36	x4DB	
+ATP Electronics	AB28L72T4SQA2	NT5DS64M4AT-7K	Nanya	SB184T04 L2 rev 2	3/14/03	2.5		(64Mx4)*36	x4DB	EOL
+Dataram	DTM63653C	K4H560438D-GCA2 rev D	Samsung	40599A rev A	2/17/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+Dataram	DTM63621H	MT46V64M4TG-75 rev C	Micron	40556 rev B	3/10/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+Avant Technology	AVM7228R38C2266 K3-A	NT5DS64M4AT-7K rev A	Nanya	BRDB45A rev A	2/13/03	2.5		(64Mx4)*36	x4DB	EOL
+ATP Electronics	AB28L72T4SQB0S	K4H560438D-TCB0 rev D	Samsung	SB184T04 L2 rev 2	3/26/03	2.5		(64Mx4)*36	x4DB	EOL
+ATP Electronics	AB28L72P4SUB0S	K4H560438D-TCB0 rev D	Samsung	SB184P04 L1	3/26/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+ATP Electronics	AB28L72P4SMB0S	K4H560438D-TCB0 rev D	Samsung	SB184P04 L1	3/28/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+Viking	VI4CR287224DYHL1	K4H560438D-TCB0 rev D	Samsung	03-0291 Rev A	3/28/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
Infineon	HYS72D128021GR-7-B	HYB25D256400BT-7	Infineon		4/22/03	2		(64Mx4)*36	x4DB	
+Avant Technology	AVM7228R38C5266 K3-A	K4H560438D-TCB0 rev D	Samsung	BRDB45A rev A	5/7/03	2.5		(64Mx4)*36	x4DB	EOL
+Viking	VI4CR287224DYHL2	MT46V64M4TG-75 rev B	Micron	03-0291 rev A	5/17/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+Centon Electronics	TOP02-D006F	MT46V64M4TG-75C rev C	Micron	LE36DDT1 844R rev A	5/19/03	2.5	Yes	(64Mx4)*36	x4DB	EOL
+Buffalo	DD266L-RW1G/SD	K4H560438D-TCB0 rev D	Samsung	4D248EF-AA	6/3/03	2	Yes	(64Mx4)*36	x4DB	
+Smart Modular Technologies	SM12872RDDR301L P-N	17329-02	Nanya	P51G184N ESZK002 rev A	6/6/03	2	Yes	(64Mx4)*36	x4DB	
+Legend	L1272YC5-PPBSDD5D	K4H560438D-TCB0 rev D	Samsung	18-21040B rev B	6/13/03	2.5	Yes	(64Mx4)*36	x4DB	EOL

**Registered, ECC, DDR266 DIMM Modules  
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Avant Technology	AVM7228R82C5266 K1-A	MT46V64M4TG -75 rev C	Micron	50-1416-01-A rev A	6/17/03	2.5	Yes	(64Mx4)*36	x4DB	
Samsung	M312L2828ET0-CA2	K4H510638E-TCA2	Samsung		6/27/03	2	Yes	(64Mx4)*36	x4DB	
ITAUCOM	01GE2665R24	MT46V64M4TG -75 rev C	Micron	0232 A	7/1/03	2.5	Yes	(64Mx4)*36	x4DB	
Samsung	M383L2828ET1-CB0	K4H510638E-TCB0	Samsung		7/14/03	2.5		(64Mx4)*18	x4DB	
+Smart Modular Technologies	SM12872RDDR3H1L P-S	K4H510638D-TCB0 rev D	Samsung	M312L2828T0	7/22/03	2.5	Yes	(64Mx4)*18	x4DB	
+TRS* Tele-Radio-Space GmbH	TRS21153	HYB25D25640 0BT-7 rev B	Infineon	M0531LA1 rev 1	7/25/03	2	Yes	(64Mx4)*18	x4DB	
+Viking	VI4CR287224DYHL3	MT46V64M4TG -75 rev C	Micron	03-0291 rev A	8/14/03	2.5	Yes	(64Mx4)*18	x4DB	
Micron	MT36VDDT12872G-265C2	MT46V64M4-75 C	Micron		8/25/03	2.5	Yes	(64Mx4)*36	x4DB	
Micron	MT36VDDT12872G-262C3	MT46V64M4FG -75E	Micron		8/25/03	2.5	Yes	(64Mx4)*36	x4DB	
Infineon	HYS72D128320GBR-7-B	HYB25D25640 0BC-7	Infineon		9/16/03	2	Yes	(64Mx4)*36	x4DB	
Samsung	M312L2920MT0-CB0	K4H510438M-TCB0	Samsung		9/16/03	2.5	Yes	(128Mx4)*18	X4SB	
+Ventura Technology Group	D54WPK28SV	K4H560438E-TCB0 rev E	Samsung	V213	10/1/03	2.5		(64Mx4)*36	x4DB	
Wintec Industries	35952756L	HYB25D25640 0AT-7 rev A	Infineon	ZK2048M8 4RBYJ	10/17/03	2.5	Yes	(64Mx4)*36	x4DB	
+ATP Electronics	AB28L72P4SMB0S	K4H560438E-TCB0 rev E	Samsung	SB184P04 L1	11/6/03	2.5	Yes	(64Mx4)*36	x4DB	
+ATP Electronics	AB28L72U4SQB0S	K4H560438E-TCB0 rev E	Samsung	SB184U04 L1	11/26/03	2.5		(64Mx4)*36	x4DB	
+Smart Modular Technologies	SM12872RDDR301L P-I	HYB25D25640 0BT-7 rev B	Infineon	P54G184N ESZKRCN rev A	12/04/03	2	Yes	(64Mx4)*36	x4DB	
+Legacy Electronics Inc.	89L6MDLR-1LDG	LED128408TA-6	Legacy	LE36DDT1 844R rev A	12/08/03	2.5	Yes	(128Mx4)*18	x4SB	
+Smart Modular Technologies	SM12872RDDR301B G-I	HYB25D25640 0BC-6 rev B	Infineon	P54G184N ESZBRCD rev A	12/23/03	2	Yes	(64Mx4)*36	x4DB	
+Legend	L1272YC5-RU1HDH5A	HY5DU12822A T-H rev A	Hyundai	DRR1U081 8-A rev 1	12/15/03	2.5	Yes	(64Mx8)*18	X8DB	
+Centon Electronics	TOP02-D026Z	MT46V64M8TG -6T rev C	Micron	DR1G872-A	1/16/04	2.5	Yes	(64Mx8)*18	X8DB	
+Swissbit	SDR12872C1A22IN-70	HYB25D25640 0BC-7 rev B	Infineon	B6R400	2/12/04	2	Yes	(64Mx4)*36	x4DB	
+TRS	TRS21174	HYB25D51280 0AT-7 rev A	Infineon	M0529LA1 rev 1	2/3/04	2	Yes	(64Mx8)*18	X8DB	
+Avant Technology	AVM7228R53C5266 K0-A	MT46V128M4T G-6T rev C	Micron	50-1415-01-B rev B	1/27/04	2.5	Yes	(128Mx4)*18	X4SB	

**Registered, ECC, DDR266 DIMM Modules  
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Smart Modular Technologies	SM12872RDDR301H P-I	HYB25D25640 0BT-7 rev B	Infineon	P58G184N ESZKGA1	2/18/04	2		(64Mx4)*36	x4DB	
+TRS	TRS21171	HYB25D25640 0BC-7 rev B	Infineon	M0533LA1 rev 1	3/3/04	2	Yes	(64Mx4)*36	x4DB	
+Dataram	DTM63686A	HYB25D25640 0BT-7 rev B	Infineon	40028A rev A	3/10/04	2		(64Mx4)*36	x4DB	
+ATP Electronics	AB28L72Q8SHB0S	K4H510838B-TCB3 rev B	Samsung	SB184Q08 L1 rev 1	4/9/04	2.5	Yes	(64Mx8)*18	X8DB	
+Avant Technology	AVM7228R38C5266 K3-A	NT5DS64M4BT -75B rev B	Nanya	BRDB45A rev A	4/9/04	2.5		(64Mx4)*36	x4DB	
+Dataram	DTM63653H	HYB25D25640 0BC-6 rev B	Infineon	40599A rev A	3/19/04	2	Yes	(64Mx4)*36	x4DB	
+Legacy Electronics Inc.	89S6JDLC-1JDG	HYB25D25640 0BT-7 rev B	Infineon	LE36DDT1 844R rev A	3/26/04	2	Yes	(64Mx4)*36	x4DB	
+Avant Technology	AVM7228R52C5266 K1-A	MT46V64M8TG (P)-75 rev C	Micron	50-1411-01-A rev A	5/6/04	2.5	Yes	(64Mx4)*36	x4DB	
+Ventura Technology Group	D54WYK25SV	K4H510838B-TCB3 rev B	Samsung	V208	4/23/04	2.5		(64Mx4)*36	x4DB	
+Viking	VI4CR287228ETHL2	MT46V64M8TG (P)-6T rev C	Micron	0000985A	5/13/04	2.5	Yes	(64Mx8)*18	x8DB	
+Ventura Technology Group	D54WYK42SV	K4H510838B-TCB3 rev B	Samsung	DR1G872-A	5/21/04	2.5	Yes	(64Mx8)*18	x8DB	
Kingmax	MPND42D-D8ST3-SBJ	K4H510838B-TCB3 rev B	Samsung	BRDA80A	6/24/04	2.5	Yes	(64Mx8)*18	x8DB	
+Smart Modular Technologies	SM12872RDDR301B GAS	K4H560438E-GCB3 rev E	Samsung	P54G184N ESZBRCD	6/17/04	2	Yes	(64Mx4)*36	x4DB	
+Viking	VI4CR287228ETHL1	MT46V64M8TG (P)-75 rev D	Micron	0000985A	7/1/04	2.5	Yes	(64Mx8)*18	x8DB	
+Dataram	DTM63698B	HYB25D51240 0BE-7 rev B	Infineon	40581A rev A	7/13/04	2	Yes	(128Mx4)*18	x4SB	
Kingston	KVR266X72RC25/1024	K4H510438B-TCB0 rev B	Samsung	2025127-001.A00	8/10/04	2.5	Yes	(128Mx4)*18	x4SB	
+Smart Modular Technologies	SM12872RDDR301B GIC	HYB25D25640 0CC-6 rev C	Infineon	P54G184N ESZBRCD	8/6/04	2	Yes	(64Mx4)*36	x4DB	
+Wintec Industries	3C953641-L	HYB25D25640 0BC-6 rev B	Infineon	ZK4096M8 4RCJB	8/13/04	2.5	Yes	(64Mx4)*36	x4DB	
+Smart Modular Technologies	SX12872RDDR308B TIB	HYB25D51280 0BE-6 rev B	Infineon	P52G184N EBZ6RCL rev B	10/1/04	2	Yes	(64Mx8)*18	x8DB	
+TRS	TRS21203	HYB25D51240 0BE-7 rev B	Infineon	M0533LA1 rev 1	10/14/04	2	Yes	(128Mx4)*18	x4SB	
+Dane-Elec	DLD266R072285M	MT46V128M4TG(P)-75 rev D	Micron	0303	11/8/04	2.5	Yes	(128Mx4)*18	x4SB	
Kingston	KVR266D4R25/1GI	HYB25D25640 0BT-7 rev B	Infineon	2025148-001.A00	3/7/05	2.5	Yes	(64Mx4)*36	x4DB	
+Swissbit	SDR12872K1A32IN-70	HYB25D25640 0CC-5 rev C	Infineon	B6R404 rev 1	3/10/05	2	Yes	(64Mx4)*36	x4DB	
+Dataram	DTM63653R	HYB25D25640 0CF-6 rev C	Infineon	40599A rev A	2/1/06	2	Yes	(64Mx4)*36	x4DB	
Smart Modular Technologies	SG12872RDDR308B TSC	K4H510838C-UCCC rev C	Samsung	PG52G184 NEBZ6RCL rev A	06-Jun-06	2.5	Yes	(64Mx8)*18		

**Registered, ECC, DDR333 DIMM Modules  
1GB Sizes (128Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Bank	EOL
+Viking	VI4CR287224DBKL2	K4H560438E-GCB3 rev E	Samsung	0000972B	9/9/04	2.5	Yes	(64Mx4)*36	x4DB	
+Buffalo	DD333L-R1G/SB	K4H510838B-TCB3 rev B	Samsung	1D188EF-AA	10/20/04	2.5	Yes	(64Mx8)*18	x8DB	
+TRS	TRS21197	HYB25D25640 OCC-6 rev C	Infineon	M0533LA1 rev 1	11/5/04	2.5	Yes	(64Mx4)*36	x4DB	
Infineon	HYS72D128320GBR-6-B	HYB25D25640 0BC-6	Infineon		11/2/04	2.5	Yes	(64Mx4)*36	X4DB	
+Avant Technology	AVM7228R52C5333 K1-MTD	MT46V64M8TG (P)-6T rev D	Micron	50-1411-01-A rev A	11/23/04	2.5	Yes	(64Mx8)*18	x8DB	
+Avant Technology	AVM7228R38C5333 K3-A	MT46V64M4TG (P)-6T rev C	Micron	BRDB45A rev A	11/29/04	2.5		(64Mx4)*36	X4DB	
+Buffalo	DD333L-R1G/MD	MT46V64M8TG (P)-6T rev D	Micron	1D188EF-AA	12/10/04	2.5	Yes	(64Mx8)*18	x8DB	
+Swissbit	SDR12872C1A22IN-60	HYB25D25640 0BC-6 rev B	Infineon	B6R400 rev A	12/17/04	2.5	Yes	(64Mx4)*36	X4DB	
+Swissbit	SDR12872K1A32IN-60	HYB25D25640 0CC-5 rev C	Infineon	B6R404 rev 1	1/31/05	2.5	Yes	(64Mx4)*36	X4DB	
+Avant Technology	AVM7228R52C5333 K1MTDP	MT46V64M8P-6T rev D	Micron	50-1411-01-A rev A	3/29/05	2.5	Yes	(64Mx8)*18	x8DB	
+Kingston	KVR333D4R25/1GI	K4H560438E-GCB3 rev E	Samsung	2025247-001.A00 na	7/28/05	2.5	Yes	(64Mx4)*36	X4DB	
+Kingston	KVR333D4R25/1GI	HYB25D25640 0CC-6 rev C	Infineon	2025247-001.A00	6/29/05	2.5	Yes	(64Mx4)*36	X4DB	
+Legend	L1272YC6-PPXSDD2E	K4H560438E-GCB3 rev E	Samsung	DR2G472B na	12/6/05	2.5	Yes	(64Mx4)*36	X4DB	
+Legend	L1272YC6-PPXSDM1B	K4H510438B-GCB3 rev B	Samsung	M312L642 0G0 na	12/14/05	2.5	Yes	(128Mx4)*18	x4SB	
<b>+Kingston</b>	<b>KVR333D4R25/1GI</b>	<b>HYB25D25640 0CF-5 rev C</b>	<b>Infineon</b>	<b>2025247-001.A00 na</b>	<b>3/16/06</b>	<b>2.5</b>	<b>Yes</b>	<b>(64Mx4)*36</b>	<b>X4DB</b>	

*Modules shaded in blue are low profile.*

*Modules in bold text do not contain Lead.*

(A) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Caution:** Some modules on this list such as “stacked” DRAM parts may have thermal & physical limitations in some chassis configurations. Configurations determined to exceed thermal limitations, may use the optional Intel Memory Cooling Fan Accessory to assist on memory cooling; refer to the platform Configuration Guide for order information.

## *Server Board SE7501HG2*

### **Registered, ECC, DDR266 DIMM Modules 2GB Sizes (256Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Rank	EOL
Infineon	HYS72D256520G R-7-A	HYB25D51240 0AT-7	Infineon		11/27/02	2	Yes	(128Mx4) *36	x4DB	
Samsung	M383L5628MT1-CA2	K4H510438M-TCA2	Samsung		4/11/03	2		(128Mx4) *36	x4DB	
+Dataram	DTM63660B	HYB25D51240 0AT-7 rev A	Infineon	40556 rev B	4/14/03	2.5	Yes	(128Mx4) *36	x4DB	EOL
MA Labs	D2GE266SAR	K4H510438M-TCB0	Samsung	M8014	4/7/03	2.5		(128Mx4) *36	x4DB	EOL
+Smart Modular Technologies	SM25672RDDR30 1LP-I	HYB25D51240 0AT-7 rev A	Infineon	P54G184NE SZKRCN rev A	5/24/03	2	Yes	(128Mx4) *36	x4DB	
+TRS* Tele-Radio-Space GmbH	TRS21155	HYB25D51240 0AT-7 rev A	Infineon	M0531LA1 rev 1	9/3/03	2	Yes	(128Mx4) *36	x4DB	
Infineon	^HYS72D256520 GR-7F-A	HYB25D51240 0AT-7F	Infineon		9/17/03	2	Yes	(128Mx4) *36	x4DB	
+Dataram	DTM63663B	HYB25D51240 0AT-7 rev A	Infineon	40556 rev B	10/30/03	2	Yes	(128Mx4) *36	x4DB	
+Legacy Electronics Inc.	8AL6MDLC-1LDG	LED128408TA-6	Legacy	LE36DDT18 44R rev A	12/10/03	2.5	Yes	(128Mx4) *36	x4DB	
Samsung	M312L5628BT0-CB0	K4H1G0638B-TCB0	Samsung		2/17/04	2.5	Yes	(128Mx4) *36	x4DB	
+Dataram	DTM63689A	MT46V128M4 FN(BN)-6 rev C	Micron	40020A rev A	3/16/04	2	Yes	(128Mx4) *36	x4DB	
+Smart Modular Technologies	SM25672RDDR30 1HP-I	HYB25D51240 0AT-7 rev A	Infineon	P52G184NE SZKGA1	4/20/04	2		(128Mx4) *36	x4DB	
+Ventura Technology Group	D56WXK28SV	K4H510438B-TCB3 rev B	Samsung	V213	4/16/04	2.5		(128Mx4) *36	x4DB	
+Legacy Electronics Inc.	8AS6MDLC-1JDG	HYB25D51240 0AT-7 rev A	Infineon	LE36DDT18 44R	6/8/04	2	Yes	(128Mx4) *36	x4DB	
Kingston	KVR266X72RC25/2G	K4H510438B-TCB0 rev B	Samsung	2025148-001.A00	8/13/04	2.5	Yes	(128Mx4) *36	x4DB	
+Dataram	DTM63689D	HYB25D51240 0BF-6 rev B	Infineon	40020A rev A	8/19/04	2	Yes	(128Mx4) *36	x4DB	
+Dataram	DTM63710A	HYB25D51240 0BE-7 rev B	Infineon	40028A rev A	1/18/05	2		(128Mx4) *36	x4DB	
+TRS	TRS21218	HYB25D51240 0BE-7 rev B	Infineon	M0531LA1 rev 1	7/26/05	2	Yes	(128Mx4) *36	x4DB	

**Registered, ECC, DDR333 DIMM Modules  
2GB Sizes (256Mx72)**

Manufacturer	Part Number	DRAM Part Number	DRAM Vendor	PCB Part Number	Date	CAS Latency	Low Profile	DRAM Organization	Rank	EOL
+Legend	L2572YC6-PPXSDM5B	K4H510438B-TCB3 rev B	Samsung	18-21040B rev B	9/17/04	2.5	Yes	(128Mx4)*36	x4DB	
+ATP Electronics	AB56L72P4SMB3S	K4H510438B-TCB3 rev B	Samsung	SB184P04L1	12/1/04	2.5	Yes	(128Mx4)*36	x4DB	
+Kingston	KVR333D4R25/2GI	HYB25D512400BC-6 rev B	Infineon	2025294-001.A00	08/18/05	2.5	Yes	128M x 4	X4DB	
+Kingston	KVR333D4R25/2GI	MT46V128M4FN-6 rev D	Micron	2025294-001.A00 na	10/21/05	2.5	Yes	(128Mx4)*36	x4DB	
+Legend	L2572YC6-PPXSMDMB	K4H510438B-TCB3 rev B	Samsung	18-21040B rev B (0403)	12/20/05	2.5	Yes	(128Mx4)*36	x4DB	

*Modules shaded in blue are low profile.*

**Modules in bold text do not contain Lead.**

(^) This is a 2-2-2 part.

(+) This vendor is part of the CMTL Certification program. This means this part has/will be tested across all compatible Intel Server Boards. For further information contact CMTL @ <http://cmtlabs.com/>

**Caution:** Some modules on this list such as “stacked” DRAM parts may have thermal & physical limitations in some chassis configurations. Configurations determined to exceed thermal limitations, may use the optional Intel Memory Cooling Fan Accessory to assist on memory cooling; refer to the platform Configuration Guide for order information.

## Sales Information

Vendor Name	Web URL	Vendor Direct Sales Info
ATP Electronics	<a href="http://www.atpinc.com/">http://www.atpinc.com/</a>	Albert Chung Tel: (1) 408-732-5831, Ext 5858 Fax: (1) 408-732-5055 <a href="mailto:sales@atpinc.com">sales@atpinc.com</a>
ATP Electronics -- Taiwan Inc.	<a href="http://www.atpinc.com/">http://www.atpinc.com/</a>	Patty Kuo Tel 011-886-2-2659-6368 Fax 886-2-2659-4982
Avant Technology	<a href="http://www.avanttechnology.com">http://www.avanttechnology.com</a>	Brad Scoggins Phone: (512)491-7411 Fax: (512)491-7412 <a href="mailto:brads@avanttechnology.com">brads@avanttechnology.com</a>
Aved Memory Products	<a href="http://www.avedmemory.com/">http://www.avedmemory.com/</a>	
Buffalo Technology	<a href="http://www.buffalotech.com/">http://www.buffalotech.com/</a>	(800) 967-0959 <a href="mailto:memory@buffalotech.com">memory@buffalotech.com</a>
Centon Electronics	<a href="http://www.centon.com">http://www.centon.com</a>	Tel: 949-855-9111 Fax: 949-855-6035
Corsair	<a href="http://www.corsairmicro.com/">http://www.corsairmicro.com/</a>	Tel: 510-657-8747 Fax: 510-657-8748
Dane-Elec	<a href="http://www.dane-memory.com/">http://www.dane-memory.com/</a>	Michal Hassan @ (949)450-2941 or email @ <a href="mailto:Michal@Dane-memory.com">Michal@Dane-memory.com</a>
Dataram	<a href="http://www.dataram.com/">http://www.dataram.com/</a>	Paul Henke, 800-328-2726 x2239 in USA 609-799-0071 <a href="mailto:phenke@dataram.com">phenke@dataram.com</a>
GoldenRAM	<a href="http://www.goldenram.com">http://www.goldenram.com</a>	Jason M. Barrette @ 800-222-861 x7546 <a href="mailto:jasonb@goldenram.com">jasonb@goldenram.com</a> or Michael E. Meyer @800-222-8861 x7512 <a href="mailto:michaelm@goldenram.com">michaelm@goldenram.com</a>
Hitachi	<a href="http://semiconductor.hitachi.com/pointer/">http://semiconductor.hitachi.com/pointer/</a>	
Hyundai/Hynix Semiconductor	<a href="http://www.heacom/">http://www.heacom/</a>	
Infineon	<a href="http://www.infineon.com/business/distribut/index.htm">http://www.infineon.com/business/distribut/index.htm</a>	
ITAUCOM	<a href="http://www.itaucom.com.br">http://www.itaucom.com.br</a>	
JITCO CO LTD	<a href="http://www.jitco.net/">http://www.jitco.net/</a>	Seong Jeon Tel: 82-32-817-9740 <a href="mailto:s.jeon@jitco.net">s.jeon@jitco.net</a>
Kingston	<a href="http://www.kingston.com">http://www.kingston.com</a>	US.- Call (877) 435-8726 Asia – Call 886-3-564-1539 Europe – Call +44-1932-755205
Legacy Electronics Inc.	<a href="http://www.legacyelectronics.com">http://www.legacyelectronics.com</a>	U.S. Contact: Gary Ridenour, 949-498-9600, Ext 350 European Contact: 49 89 370 664 11
Legend	<a href="http://www.legend.com.au">http://www.legend.com.au</a>	
Micron	<a href="http://silicon.micron.com/mktg/">http://silicon.micron.com/mktg/</a> <a href="http://silicon.micron.com/mktg/mbqual/qual_data.cfm">http://silicon.micron.com/mktg/mbqual/qual_data.cfm</a>	
MSC Vertriebs GmbH	<a href="http://www.msc-ge.com">http://www.msc-ge.com</a>	William Perrigo 49-7249-910-417 Fax: 49-7249-910-229 <a href="mailto:wpe@msc-ge.com">wpe@msc-ge.com</a>

Vendor Name	Web URL	Vendor Direct Sales Info
Netlist, Inc	<a href="http://www.netlistinc.com">http://www.netlistinc.com</a>	Christopher Lopes 949.435.0025 tel 949.435.0031 fax <a href="mailto:sales@netlistinc.com">sales@netlistinc.com</a>
Peripheral Enhancements	<a href="http://www.peripheral.com/">http://www.peripheral.com/</a>	
Samsung	<a href="http://www.korea.samsungsemi.com/locate/buy/list_na.html">http://www.korea.samsungsemi.com/locate/buy/list_na.html</a>	For US customers go to: <a href="http://www.mymemorystore.com/">http://www.mymemorystore.com/</a>
Silicon Tech	<a href="http://www.silicontech.com/contact/salescontacts.shtml">http://www.silicontech.com/contact/salescontacts.shtml</a>	
Simple Tech	<a href="http://www.simpletech.com">http://www.simpletech.com</a>	Ron Darwish @ (949) 260-8230 or email @ <a href="mailto:Rdarwish@Simpletech.com">Rdarwish@Simpletech.com</a>
SMART Modular Technologies	<a href="http://www.smartm.com/channel">http://www.smartm.com/channel</a>	Gene Patino (949) 439-6167 <a href="mailto:Gene.Patino@Smartm.com">Gene.Patino@Smartm.com</a>
Swissbit	<a href="http://www.swissbit.com">http://www.swissbit.com</a>	Tony Cerreta Tel: 914-935-1400 x240 Fax: 914-935-9865 <a href="mailto:tony.cerreta@swissbitna.com">tony.cerreta@swissbitna.com</a>
TechnoLinc Corporation	<a href="http://www.technolinc.com">http://www.technolinc.com</a>	David Curtis 510-445-7400 <a href="mailto:davide@technolinc.com">davide@technolinc.com</a>
TRS* Tele-Radio-Space GmbH	<a href="http://www.certified-memory.com">http://www.certified-memory.com</a> <a href="http://www.certified-memory.de">http://www.certified-memory.de</a>	Vendor Direct Sales Info: Andreas Gruendl Tel: +49.89.945532-34 Fax: +49.89.945532-41 <a href="mailto:Andreas.gruendl@trs-eu.com">Andreas.gruendl@trs-eu.com</a>
Unigen	<a href="http://www.unigen.com">http://www.unigen.com</a>	
Ventura Technology Inc	<a href="http://www.venturatech.com">http://www.venturatech.com</a>	Sam Lewis 760 599-0080 ext. 1
Viking InterWorks	<a href="http://www.vikinginterworks.com">http://www.vikinginterworks.com</a>	
Virtium Technology Inc	<a href="http://www.virtium.com">http://www.virtium.com</a>	Tod Skelton @ (949) 460-0020 ext. 146 or email @ <a href="mailto:tod.skelton@virtium.com">tod.skelton@virtium.com</a>
Legend	<a href="http://www.legend.com.au">http://www.legend.com.au</a>	Tel: 800-338-2361 Fax: 949-459-8577 <a href="mailto:orderdesk@vikingcomponents.com">orderdesk@vikingcomponents.com</a>
Wintec Industries	<a href="http://www.wintecindustries.com">http://www.wintecindustries.com</a>	Tel 510-360-6300 Fax 510-770-9338



### **CMTL\* (Computer Memory Test Labs)**

CMTL is a privately owned and operated memory testing organization responsible for testing a broad range of memory products. Memory devices tested by CMTL must undergo a rigorous battery of tests to ensure that the product will perform the intended server functions. Memory capability is a major factor your customers consider. CMTL has the ability to test and certify memory on Intel-based server platforms. The list of memory modules, which have undergone testing through the CMTL facility, should be referenced when considering modules for integration into this Intel server product. Stringent standards with regard to manufacturing procedures and quality must be met to pass the exacting tests required for qualification through the independent testing facility. Testing is performed by CMTL with Intel server products and test procedures defined by Intel's Memory Validation Lab. Intel routinely audits the CMTL facility to ensure all procedures, process handling, and testing methodologies are met.

#### **IMPORTANT NOTE**

DIMM devices with gold contacts should NOT be placed into DIMM sockets with tin-lead contacts or vice-versa. Mixing dissimilar metal contact types has been shown to result in unreliable memory operation. Intel recommends similar manufacturer and similar speeds in each bank on the memory module. Mixing of dissimilar memory manufacturer devices or dissimilar memory device speeds is not recommended. This document contains information which is the proprietary property of Intel Corporation. Nothing in this document constitutes a guaranty, warranty, or license, express or implied. Intel has tested the following DIMMs for minimum electrical and functional compatibility with boxed processors. This listing is not intended to be all inclusive; it only represents the DIMMs Intel or CMTL has tested. Users of this list are reminded to check with the DIMM manufacturer or Distributor to ensure that a particular DIMM model is adequate for the intended purpose on the boxed processor baseboard. Intel provides no indemnities for and expressly disclaims all liabilities for any and all such guaranties, representations, and warranties (oral or written) whether express or implied, related to DIMMs in a Intel® Server Board product, including without limitation to: fitness for a particular purpose; merchantability; noninfringement of intellectual property or other rights of any third party or of Intel. The reader is advised that third parties may have intellectual property rights which may be relevant to this document and the technologies discussed herein, and is advised to seek the advice of competent legal counsel, without obligation of Intel. Intel retains the right to make changes to this document at any time, without notice. Intel makes no warranty or representation with respect to the use of this document or reliance by the reader upon its contents, and assumes no responsibility for any errors which may appear in the document nor does it make a commitment to update the information contained herein.

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